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PATENTS
112055-0040P1
17732-38560.001

IN THE CLAIMS:

- 1 1. (currently amended) A die containing package comprising:
 - 2 a die defining electrical die contacts,
 - 3 a substrate defining first substrate contacts,
 - 4 flattened electrical conductive balls attached to the die contacts and making
 - 5 electrical connection thereto,
 - 6 electrical conductive runs on the substrate connecting the first substrate contacts
 - 7 to second substrate contacts,
 - 8 electrically conductive wires with first ends making electrical connections to
 - 9 the first substrate contacts, wherein the wires are formed to run substantially parallel to
 - 10 the surface of the die, and wherein the other ends are horizontally attached to the flat-
 - 11 tened balls. are arranged making electrical connections to the flattened electrical con-
 - 12 ductive balls attached to the die contacts, and wherein the other ends remain substan-
 - 13 tially parallel to the surface of the die as they make electrical connections to the flat-
 - 14 tened electrical conductive balls.
- 1 2. Canceled.
- 1 3. (previously presented) The die containing package of claim 1 wherein the second
 - 2 substrate contacts are located on the substrate opposite the first substrate contacts.
- 1 4. (previously presented) The die containing package of claim 1 wherein the second
 - 2 substrate contacts are located on the substrate to accommodate a pin out different from
 - 3 the die.

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1 5. (currently amended) A process for packaging a die comprising the steps of:
2 defining electrical die contacts,
3 defining a substrate with first substrate contacts,
4 flattening electrical conductive balls,
5 attaching the flattened electrically conductive balls to the die contacts,
6 forming electrical conductive runs on the substrate connecting the first substrate
7 contacts to second substrate contacts,
8 connecting electrically conductive wires to the first substrate contacts,
9 running the electrically conductive wires substantially parallel to the surface of
10 the die to the die contacts, and
11 ~~making electrical connections from~~ horizontally attaching the other ends of the
12 wires to the flattened electrical conductive balls thereby making electrical connections
13 ~~therebetween attached to the die contacts~~, and wherein the other ends remain substan-
14 tially parallel to the surface of the die ~~as they make electrical connections to the flattened~~
15 ~~electrical conductive balls.~~

1 6. Canceled.

1 7. (previously presented) The process of claim 5 further comprising the step of locating
2 the second substrate contacts on the substrate opposite the first substrate contacts.

1 8. (previously presented) The process of claim 5 further comprising the step of locating
2 the second substrate contacts on the substrate to accommodate a pin out different from
3 the die.